

## **LISTING OF CLAIMS:**

- 1-3 (previously canceled)
4. (previously presented) A transfer member having at least a supporting member and a light emitting layer formed peelably on the supporting member, wherein a bonding property improving substance is included in the layer of the transfer member to be contacted with a member to be transferred.
5. (previously presented) The transfer member according to claim 4, wherein the layer including the bonding property improving substance is a hole transporting layer, an electron transporting layer or a light emitting layer.
6. (previously presented) A member to be transferred having at least a base member and an electrode formed on the base member, wherein a bonding property improving substance is included in the layer of the member to be transferred to be contacted with a transfer member.
7. (previously presented) The member to be transferred according to claim 6, wherein the layer including the bonding property improving substance is a hole transporting layer or an electron transporting layer.
8. (new) An organic EL element having at least a base member, a first electrode formed on the base member, an organic EL light emitting layer formed on the first electrode and a second electrode formed on the organic EL light emitting layer, wherein a bonding property improving substance is included in the organic EL light emitting layer.
9. (new) An organic EL element having at least a base member, a first electrode formed on the base member, a electron transporting layer and a light emitting layer formed on the first electrode and a second electrode formed on the electron transporting layer and the light emitting layer, wherein a bonding property improving substance is included in the electron transporting layer.
10. (new) An organic EL element having at least a base member, a first electrode formed on the base member, a hole transporting layer and a light emitting layer formed on the first electrode and a second electrode formed on the hole transporting layer and the light emitting layer, wherein a bonding property improving substance is included in the hole transporting layer.